Burn-In Sockets MPS Series OPEN TOP eMMC SOCKET





Open Top Style. Accommodates Chip Scale Package with 0.5mm pitch. Compact size and low actuation force.

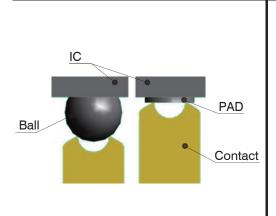
4-point pinch design for enhanced electrical contact.

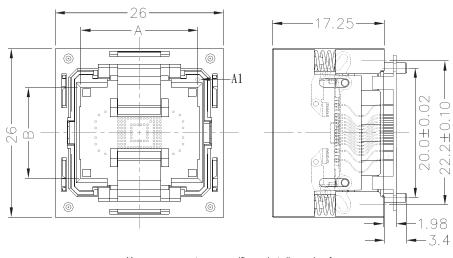
Field exchangeable package location plate.

"U" contact supports any pad or solder ball shape and composition.

Please note, we will always request the chip data to ensure we offer a compatible socket.



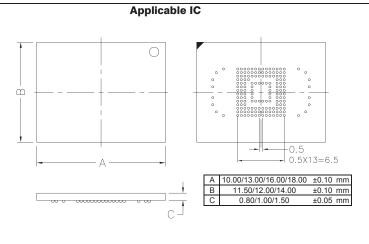




You may request any specific socket dimension from info@e-tec.com

For top view socket dimension pls. ref. to separate catalog page

Contact Tip Detail



Specifications

Mechanical data

Contact life 25,000 cycles
Contact Normal Force 3-5g Per Pin
Operation Force 2.0Kg max.

Material

Insulator (RoHS compliant)
Contact (RoHS compliant)

PES , PEI Beryllium Copper Alloy Gold cover Nickel

Contact plating Electrical data

 $\begin{array}{lll} \text{Contact resistance} & < 30 \text{ m}\Omega \\ \text{Current rating} & 1\text{A} \\ \text{Insulation resistance at 500V DC} & 1,000 \text{ m}\Omega \end{array}$

Operating temperature -55°C to +175°C

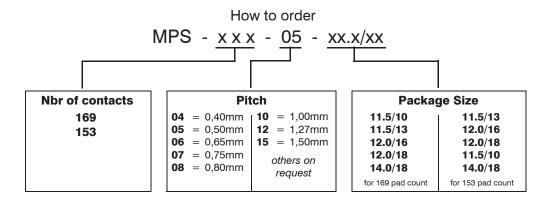
Recommendations:

Solder paste – Please use a solder paste w/o any silver! Solder profile – Please refer to our website www.e-tec.com

E-tec solderless sockets are adapted to a standard PCB thickness of 1.60mm. For a different PCB thickness, please inform E-tec first!

For high pincount SMT sockets, E-tec recommends the use of a pluggable thru-hole socket mounted into a MiniGrid Adapter (see also page 10, 11 & 12 for more details)

For SMT sockets in general, E-tec recommends the use of locating pegs which can be soldered to the PCB for added mechanical strength.



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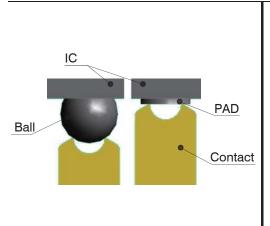
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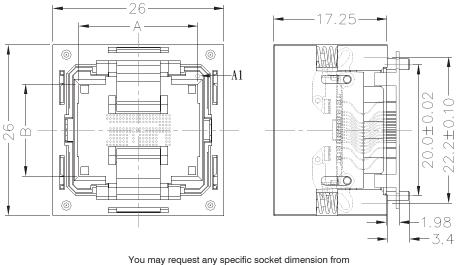
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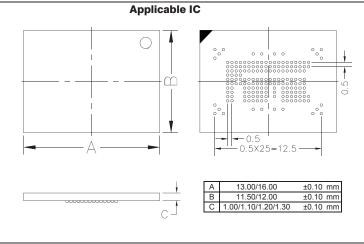






Contact Tip Detail

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Specifications

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Material

PES . PEI Insulator (RoHS compliant) (RoHS compliant) Contact

Contact plating

Beryllium Copper Alloy Gold cover Nickel

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Operating temperature -55°C to +175°C

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